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Western Development Laboratories
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QUARTERLY STATUS REPORT - Report Period of 1 August
to 1 November 1966

RELIABILITY STUDY ON ZENER DIODES USED IN THE SATURN PROGRAM

CONTRACT NO. NAS 8-20315

Quarterly technical report No. 1 on the status of the Zener Diode Reliability Study in accordance with WDL-TP 2114 and NASA Procurement Request DCN 1-6-60-00029.

This quarterly report covers in detail the current status of Tasks 1, 2, and 3. These tasks are described in the WDL Test Proposal 2114 are respectively: 1) Information Study and Survey; 2) Parts Procurement and 3) Step Stress Matrix Evaluation. The tasks are discussed below in their consecutive order.

Task 1 - Information Study and Survey

WDL engineering has reviewed the up to date listings and reports submitted through the Interservice Data Exchange Program (IDEP) for a basic indication of zener diode manufacturers and their respective failure modes. The results of this inquiry are summarized in Table I. This information coupled with information obtained from FARADA (Failure Rate Data) and WDL's accumulated data from various Air Force and NASA programs has allowed for the initial vendor selection of TRW Electronics, Motorola Semiconductor Inc. and Dickson Electronics Corp. It should be noted here that these vendors all hold current military qualification of the 400 m Watt zener diode series although this was not established as a definite requirement of this test program. A WDL specification was generated for the test sample procurement (WDL-SL-171723) of 3,000 ea. zener diodes comprised of the three manufacturers and three selected voltage ranges; JEDEC 1N746A (3.3V), 1N758A (10.0) and 1N980B (62.0V). The Purchase Order was let 8/3/66.

HC \$1.00
M.F. 1.50

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TABLE I

IDEP SUMMARY OF VARIOUS MANUFACTURERS VS.
QUANTITY OF FAILURES

<u>MANUFACTURER</u>	<u>NO. TEST UNITS</u>	<u>NO. FAILURES TOTAL</u>	<u>PERCENTAGE FAILURES</u>
Continental Device Corp. (CDC)	231	23	9.9%
Delta Semiconductors	60	16	26.7%
Dickson Electronics	100	2	2.0%
Motorola Semiconductors	175	10	5.7%
Texas Instruments Corp.	260	21	8.1%
Transitron Electronics Corp.	231	23	9.9%
TRW Electronics	159	8	5.0%

Task 2 - Parts Procurement

The zener diode procurement effort is continuing and of this date the following diodes have been received:

<u>Manufacturer</u>	<u>Received</u>	<u>To be Received</u>
Dickson	800 all types	133 ea. of 1N980B
Motorola	666 of 1N758A & 1N980B 155 of 1N746A	179 of 1N746A
TRW	666 of 1N746A & 1N758A	333 ea. of 1N980B

An approximate 45 day delay has been incurred because of slow delivery by all part vendors. The reason given by both TRW and Dickson was that of low yield of the high voltage zener diodes during manufacturing caused late shipments. Motorola has not submitted any reason for late shipment. In any case, the now scheduled date for the receipt of all test samples is 15 Nov. 1966.

Task 3 - Step Stress Matrix Evaluation.

As of this report, all test samples which have been received are now serialized using Brady high temperature labels. One diode from each manufacturer has been stripped of paint to verify and examine the manufacturer's construction of interior elements.

Work has been completed on all required test fixtures including the setting up of a measurement station which will allow for IBM 526 data print out of all basic measurement parameters. A computer program has been set up to present

all data in an easily presentable format. Attachments are included of the basic electrical measurement test methods and a copy of the proposed data analysis format. The computer return will provide between electrical measurements the absolute difference value and percent change of each parameter measured. In addition, each test group, such as the High Temperature Operation Group, will have computed at measurement the group mean \bar{x} and standard deviation σ . All devices which do not meet specified test limits will be tabulated separately.

Attachment A contains a copy of the Phase I. Step Stress Evaluation, part of this test program. Initial electrical measurements are now underway on $1/f$ and multistate noise measurements. During the next quarterly report period, it is expected that the step stress matrix testing will be completed, data analysis completed, failure modes identified and the needed screening recommendations presented.


W. D. Boltz
Sr. Engineer

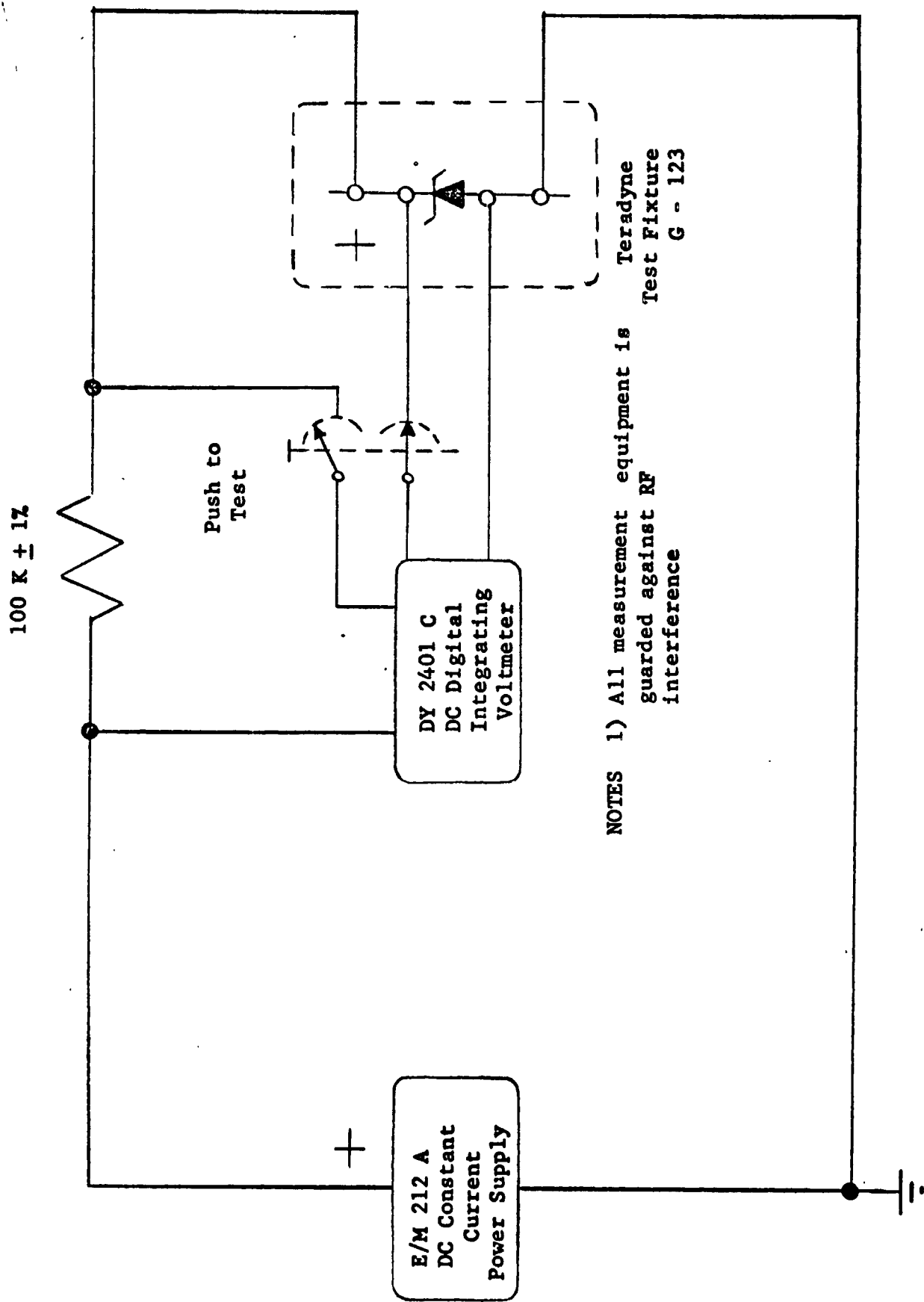
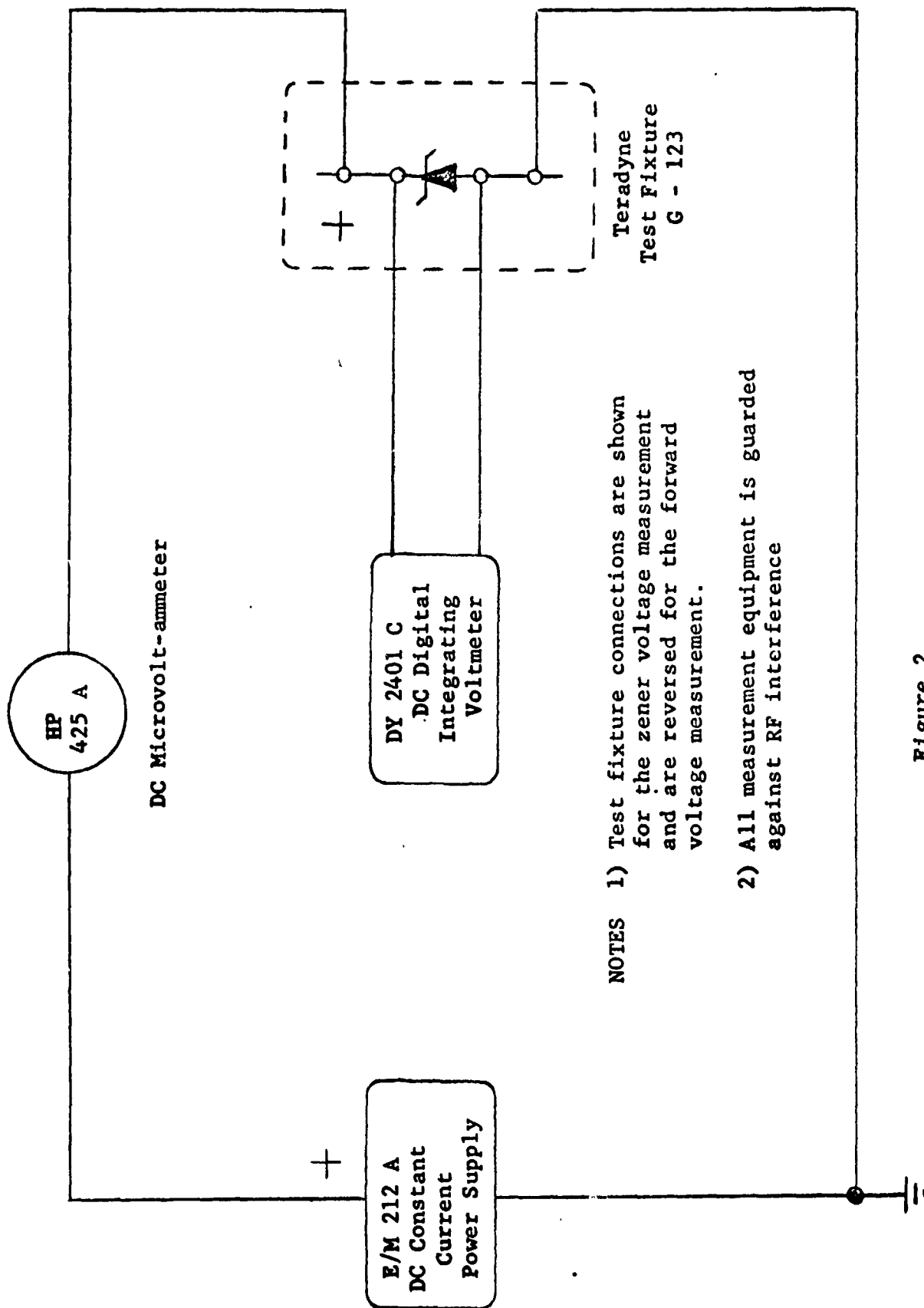


Figure 1

Basic Schematic of Leakage Current Measurement



- NOTES
- 1) Test fixture connections are shown for the zener voltage measurement and are reversed for the forward voltage measurement.
 - 2) All measurement equipment is guarded against RF interference

Figure 2
BASIC SCHEMATIC OF FORWARD VOLTAGE
AND ZENER VOLTAGE MEASUREMENT

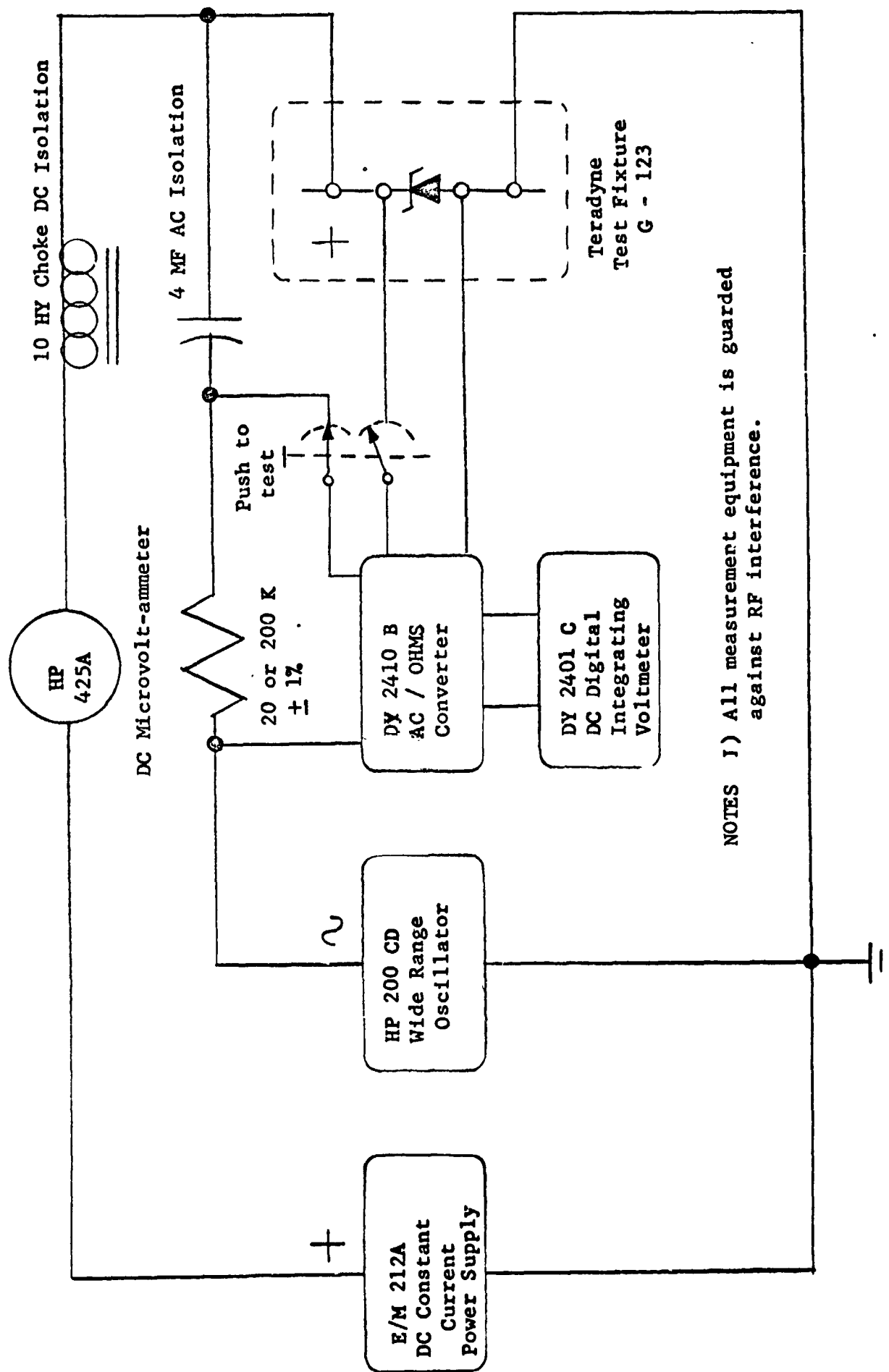


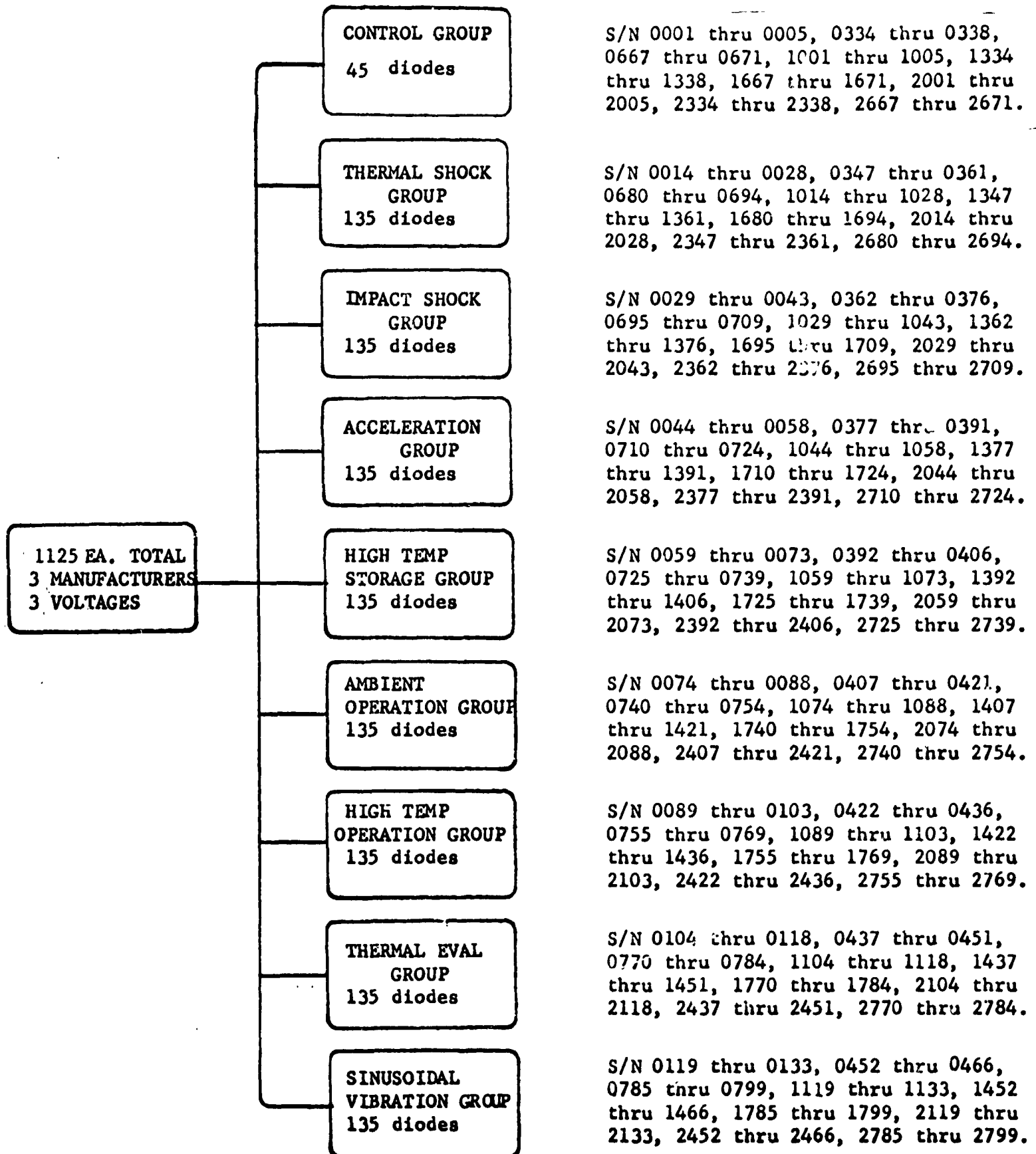
Figure 3
BASIC SCHEMATIC OF ZENER IMPEDANCE MEASUREMENT

TEST FLOW CHART PHASE I- STEP STRESS MATRIX EVALUATION

ATTACHMENT A

PHASE I
STEP STRESS EVALUATION
TEST FLOW DIAGRAM

WDL TP 1544-25
3 October 1966



EXAMPLES OF DATA CARD AND DATA STATISTICS COMPUTER RETURNS

ATTACHMENT B

PHILCO FORD SRS DIVISION TEST RESULTS PROJECT: NASA EVAL TEST NAS 8 20315 PAGE 0001
TYPE 1N746A REV D LOT 6623 CARD GROUP 1 TEST PROCEDURE 1544-25

TEST CONDITION CODES AND DESCRIPTIONS:

UNIT CODE	DESCRIPTION				
0000 E1	GROUP E OHR MEAS. HIGH TEMP OP LIFE S/N 0001-0038				
0000 E3	GROUP E 670 HR MEAS. HIGH TEMP OR LIFE S/N 0001-0038				
UNIT CODE	1	2	3	4	5
	I _R	V _F	V _Z	Z _Z	Z _{ZK}
	MIC AMPS	VOLTS	VOLTS	OHMS	OH'S
0001 E1	0.012	0.971	9.250	178.7	2530
0001 E3	0.006	0.969	9.280	191.4	1110
E1-E3 CHG	-0.006	-0.002	+0.030	+017.7	-1420
% CHG	-50%	-<1%	+<1%	+7%	-56%
MEAN X:	+0.006	+0.970	+9.265	+184.1	+1820
STANDARD DEV. X:	+0.006	+0.970	+9.265	+184.1	+1820

[illegible]

CURRENT MEASUREMENTS ARE RECORDED IN 10^{-12} AMP (PICO AMP)
VOLTAGE MEASUREMENTS ARE RECORDED IN 10^{-3} VOLT (MILLIVOLT)
IMPEDANCE MEASUREMENTS ARE RECORDED IN 10^{-3} OHM (MILLIOHM)
DECIMAL IS LOCATED BETWEEN 3RD & 4TH DIGIT OF DATA

EXAMPLE OF DATA CARD FORMAT

[illegible]